

# Continuous Processing of High Thermal Conductivity Polyethylene Fibers and Sheets

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# Project Objective

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- Plastics are *less expensive, lighter, and require less energy to process than metals*; however, they have low thermal conductivity values ( $\sim 0.3$  W/mK)
- Thermal conductivity is an important consideration in choosing materials for *energy applications*
- We are developing a *continuous fabrication process* for high thermal conductivity polyethylene (PE) films
- While high thermal conductivity in (PE) has been shown in isolated nanofibers, real world commercial applications require a different form factor and fabrication process

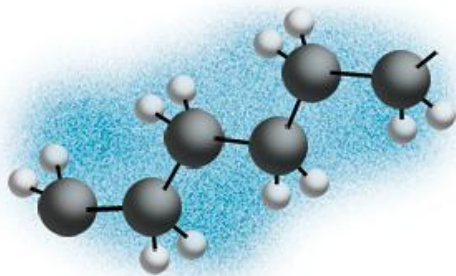
# Technical Approach

No commercially available pure polymers with high thermal conductivity

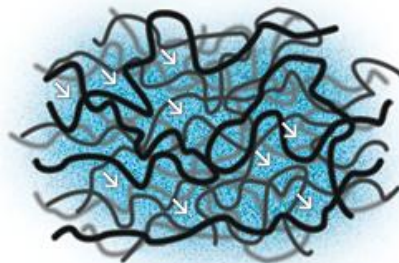
## Concept:

- A single extended polymer chain can have high thermal conductivity due to the C-C bond
- In bulk polymers, however, due to entanglements and defects thermal conductivity drops significantly
- We aim to fabricate a continuous film with high thermal conductivity by disentangling and aligning polymer chains
- Successfully demonstrated in 100 nm single fibers ( $\sim 100$  W/mK)<sup>1</sup>

*Polymer  
microstructure*



*Chain orientation  
in amorphous  
polymer*



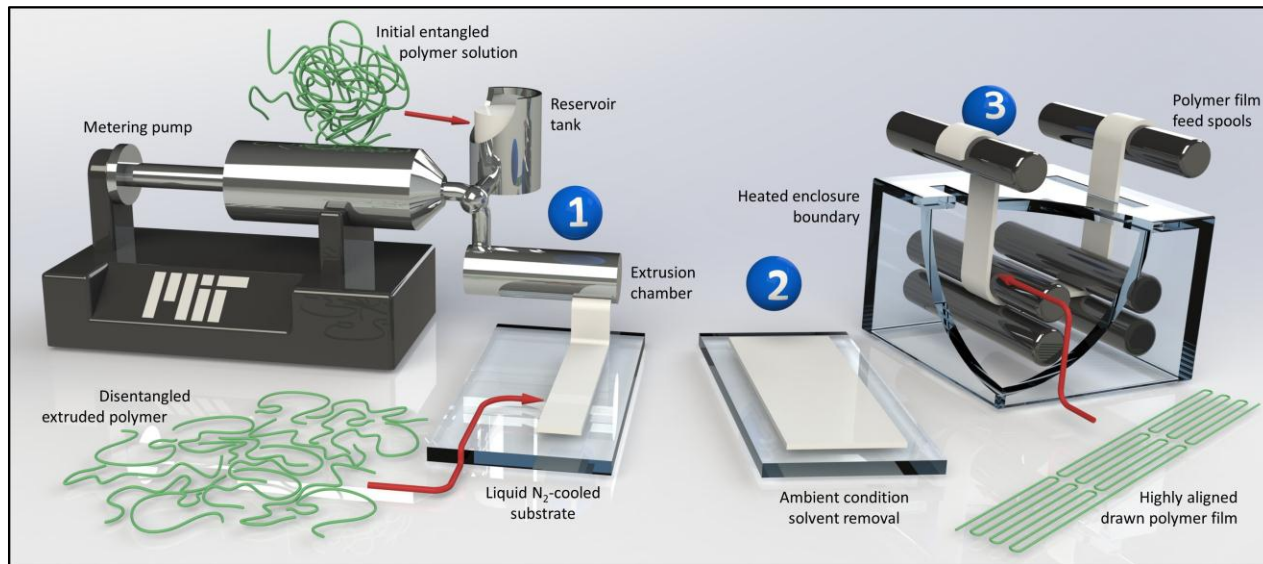
*Chain  
orientation in  
drawn polymer*



<sup>1</sup>S. Shen, A. Henry, J. Tong, R. Zheng, and G. Chen, Nat Nano **5**, (4), (2010).

# Technical Approach

- We developed a 3-stage continuous fabrication process
- In BP2 incorporated mixed solvents, mixed PE polymers, 2<sup>nd</sup> generation fabrication platform to achieve higher draw ratios



- **Thermal characterization:**
  - ❑ Built custom systems (based on the Angstrom and steady-state methods) to measure in-plane thermal conductivity
  - ❑ Tested single layer films as well as instrumented laminated samples

# Transition and Deployment

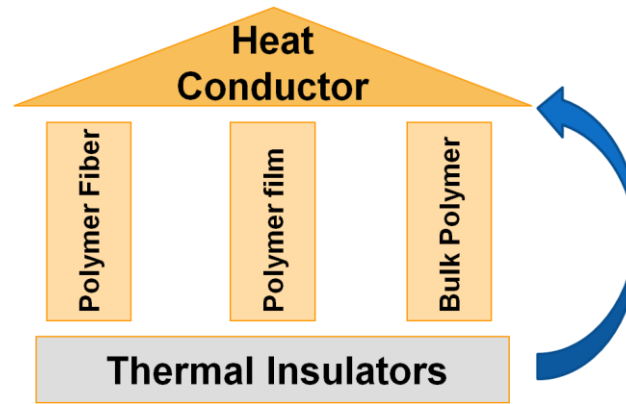
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- **End users:**
  - ❑ Electronic packaging & thermal management
  - ❑ Heat exchangers, HVAC, etc.
  - ❑ We have held preliminary discussions with UTRC, and several companies working on various energy efficient devices
- **Mission/capability improvements:** Cost reduction, weight reduction, highly chemical resistant, bio-compatible, electrically isolating, and highly thermally conductive
- **Examples of usage:** Heat exchanger fins, **wearable devices**, and cases/housing for electronics, and cooling for stroke victims
  - ❑ Considering performance-based embodied energy as a FOM, UHMWPE fins in heat exchangers provide 4,126 MJ/KW; current Ti-based fins in seawater treatment are 6,483 MJ/KW (source ORNL)
- **Commercialization approach & technology sustainment model**
  - ❑ We are currently in TRL<sub>3</sub>
  - ❑ A technology sustainment study will be conducted in budget period 3

# Measure of Success

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- If you're successful, what difference will it make?



- **What impact will success have:** Breakthrough in heat management systems using innovative polymer plastic
- **How will it be measured:** High thermal conductivity, ease of synthesis, good chemical stability, cost/energy savings, and the potential for scale-up
- **What is the potential energy impact? Economic impact?**
  - ❑ Significant fabrication energy savings (compared to metal forming/working)
  - ❑ Polyethylene is also cheap and abundant

# Project Management & Budget

- **Project duration:** 3 years
- **Tasks and milestones:** Quarterly milestone targets and annual go/no-go criteria

Budget period	Go/no-go Description	Verification method	Completion date
1	Development of 1st generation PE processing apparatus	Demonstrate PE sheet ( $1 \times 5 \text{ cm}^2$ ) fabrication	Completed as of 10/1/13
2	Development of 2nd generation PE processing apparatus	Achieve 30 W/mK in the PE films	Completed as of 12/1/14
3*	Development of 3rd generation PE processing apparatus	Achieve 60 W/mK in the PE films	

\*Currently at >40 W/mK

Total Project Budget	
DOE Investment	\$1M
Cost Share	\$0
Project Total	\$1M

# Results and Accomplishments

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- **Project status:** Developed a continuous platform for fabrication of polyethylene films with thermal conductivity ( $k$ ) of  $>40 \text{ W m}^{-1}\text{K}^{-1}$
- **Patent filed on fabrication system**
- **Completed milestones:**
  - ❑ Commissioned/optimized 2<sup>nd</sup> generation innovative fabrication platform
  - ❑ Developed effective media model to predict the  $k$  of the ultradrawn films
  - ❑ Characterized thermal properties and microstructure of single layer and laminated films
- **Results to report:**
  - ❑ Demonstrated polyethylene films with thermal conductivity of  $>40 \text{ W m}^{-1}\text{K}^{-1}$  (commercial films have thermal conductivity of  $\sim 0.3 \text{ Wm}^{-1}\text{K}^{-1}$ )
- **Future/ongoing work:**
  - ❑ Achieve final thermal conductivity of  $60 \text{ W m}^{-1}\text{K}^{-1}$
  - ❑ Modification/optimization of microstructure/chemistry/fabrication procedure of the films to reach the goal of the project